34. (Original) The method of claim 33, wherein forming a metal line air-bridge structure includes forming the number of multilayer metal lines from a group consisting of Aluminum, Copper, Silver, and Gold.

35. (Original) The method of claim 33, wherein forming a metal line air-bridge structure includes forming a first conductor bridge level.

36. (Original) A method, comprising:

connecting a number of multilayer metal lines to a number of silicon devices in a substrate;

forming a lightly doped silicide layer on the number of multilayer metal lines;

hermetically sealing underlying metal lines with the silicide layer and an oxide layer on the silicide layer;

forming a low dielectric constant insulator in a number of interstices between the number of multilayer metal lines and the substrate; and

wherein the silicide layer on the number of multilayer metal lines.

37. (Currently Amended) A method, comprising:

forming a metal line air-bridge structure, which has ~~having~~ a number of top, bottom, and side exposed surfaces adjacent to a number of interstices in the air-bridge structure and connects to a number of silicon devices in a substrate;

covering the exposed surfaces of the air-bridge structure with a silicide layer;

hermetically sealing metal lines of the air-bridge structure underlying a nitride layer on the silicide layer ~~and the silicide layer~~; and

providing a low dielectric constant insulator in the number of interstices.

DO NOT Enter at line 1 of claim 37, see Ex's Amendment for claim 37 M.T. 4/6/06

38. (Original) The method of claim 37, wherein forming a metal line air-bridge structure includes forming a number of multilayer metal lines from a group consisting of Aluminum, Copper, Silver, and Gold.